



Financial Results of FY2024

From April 1, 2024 to March 31, 2025

SHINKO ELECTRIC INDUSTRIES CO., LTD.

Brightening the Future
Since 1946



Financial Results Overview of FY2024 (consolidated)

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Financial Results Overview of FY2024 (consolidated)

Financial Results

(Billions of yen)

	FY2023 (Result)	FY2024 (Result)	YoY	
			Amount	Ratio of Change
Net Sales	210.0	215.0	+5.1	+2%
Operating Profit (Ratio against Net Sales)	24.8 (12%)	25.4 (12%)	+0.5	+2%
Ordinary Profit (Ratio against Net Sales)	27.3 (13%)	25.1 (12%)	-2.1	-8%
Profit* (Ratio against Net Sales)	18.6 (9%)	17.9 (8%)	-0.7	-4%

* Profit attributable to owners of parent

Earnings per Share	137.73yen	132.30yen
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Financial Results Overview of FY2024 (consolidated)

Summary of Financial Statements

- As for the semiconductor industry, demand for AI continued to grow, and the semiconductor manufacturing equipment market remained strong mainly for capital investment for AI. On the other hand, tough market conditions continued, in which the semiconductor industry as a whole continued to be unable to achieve a full-fledged recovery, as demand for general-purpose servers, automobiles, and industrial equipment, etc. was remaining sluggish, and the industry was affected by prolonged inventory adjustments and other factors, moreover bifurcation of demand trends became more clear.
- As for the Shinko Group, net sales of ceramic electrostatic chucks for semiconductor manufacturing equipment grew due to increased demand against the backdrop of expanded capital investment in semiconductors for AI; etc., and net sales of IC assemblies increased due to expanded demand for high-end smartphones, etc. and other factors. On the other hand, net sales of flip-chip type packages decreased due to the impact of delay in demand recovery for servers as well as intensified competition for PCs and other factors.
- Net sales up 2% year on year. Ordinary profit and profit down due to lower sales of flip chip type packages and other factors.

Financial Results Overview of FY2024 (consolidated)

Net Sales and Ordinary Profit by Business Segment

(Billions of yen)

		FY2023 (Result)		FY2024 (Result)		Ratio of Change (YoY)
Net Sales *1	Plastic Packages	127.8	Represent % of Net Sales [61%]	122.7	Represent % of Net Sales [57%]	− 4%
	Metal Packages	73.9	[35%]	84.1	[39%]	+14%
	Others	8.3	[4%]	8.3	[4%]	− 1%
	Total	210.0	[100%]	215.0	[100%]	+2%
Ordinary Profit *2	Plastic Packages	11.8	Ratio against Net Sales (9%)	5.4	Ratio against Net Sales (4%)	− 55%
	Metal Packages	16.1	(22%)	20.2	(24%)	+26%
	Others/Adjustment	− 0.7		− 0.5		
	Total	27.3	(13%)	25.1	(12%)	− 8%

*1 Sales to external customers

*2 Before inter-segment transaction adjustment

Financial Results Overview of FY2024 (consolidated)

Financial Status, Capital Expenditure and Depreciation

(Billions of yen)

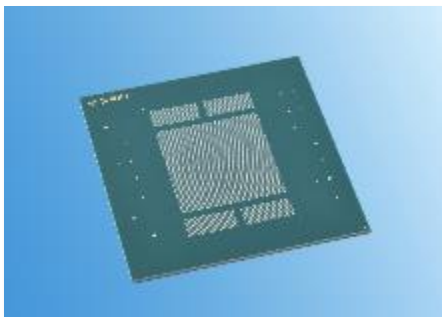
	FY2023	FY2024
Total Assets	393.8	397.1
Net Assets	265.0	283.4
Equity Ratio	67%	71%

	FY2023	FY2024
Capital Expenditure*	63.7	19.4
Depreciation*	27.4	26.4
Research and Development	3.5	4.1
Exchange Rates (Yen/US dollar)	143	150

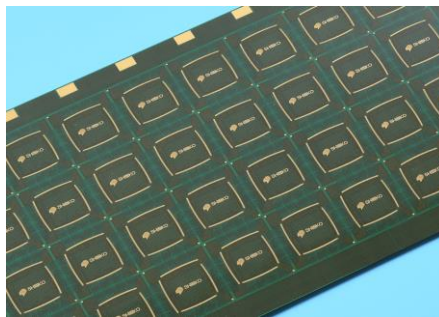
* Except intangible assets

Financial Results Overview of FY2024 (consolidated)

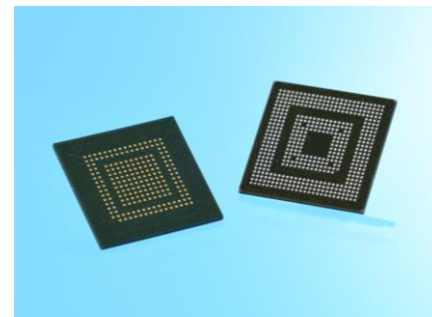
Plastic Packages



**Flip-Chip Type
Package**



**Plastic BGA
Substrates**



IC Assemblies

【Applications】

PCs, Servers, Smartphones, Consumer Products, etc.

Financial Results Overview of FY2024 (consolidated)

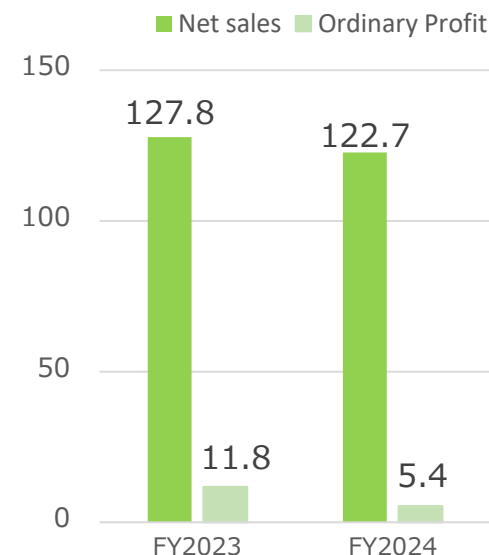
Plastic Packages

(Billions of yen)

	FY2023 (Result)	FY2024 (Result)	YoY	
			Amount	Ratio of Change
Net Sales	127.8 [61%] ^{*1}	122.7 [57%] ^{*1}	- 5.1	- 4%
Ordinary Profit	11.8 (9%) ^{*2}	5.4 (4%) ^{*2}	- 6.5	- 55%

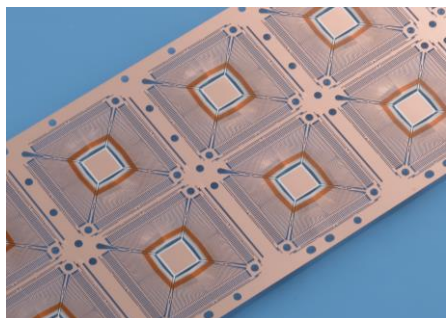
*1 Represent % of Net Sales * 2 Ratio against Net Sales

- Net sales of flip-chip type packages decreased due to the impact of delay in demand recovery for servers as well as intensified competition for PCs and other factors.
- Net sales of plastic BGA substrates decreased due to the impact of inventory adjustments in advanced memory, etc. and other factors.
- Net sales of IC assemblies increased due to expanded demand for high-end smartphones, etc. and other factors.

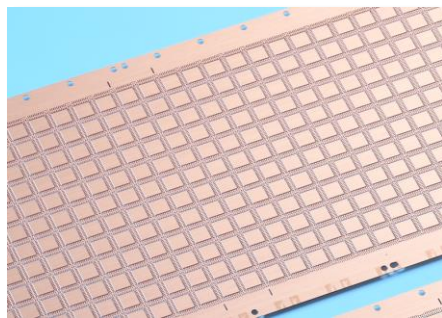


Financial Results Overview of FY2024 (consolidated)

Metal Packages



Stamped Leadframes



**Etched Leadframes
(QFN-Type)**



**Ceramic Electrostatic
Chuck**



Glass-to-Metal Seals



Heat Spreaders

【Applications】

**Automobiles, Smartphones, Consumer Products, Semiconductor
Manufacturing Equipment, Communications Equipment, etc.**

Financial Results Overview of FY2024 (consolidated)

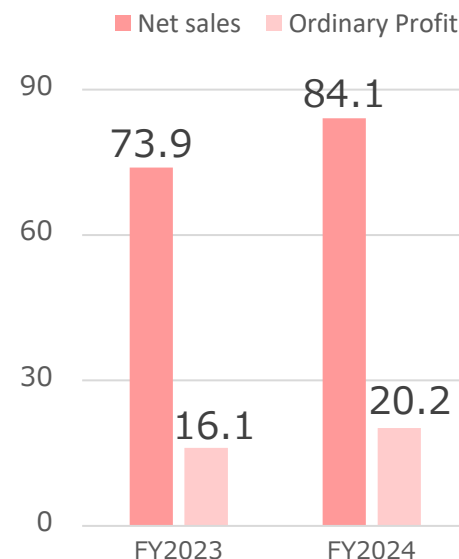
Metal Packages

(Billions of yen)

	FY2023 (Result)	FY2024 (Result)	YoY	
			Amount	Ratio of Change
Net Sales	73.9 [35%] * 1	84.1 [39%] * 1	+10.2	+14%
Ordinary Profit	16.1 (22%) * 2	20.2 (24%) * 2	+4.1	+26%

* 1 Represent % of Net Sales * 2 Ratio against Net Sales

- Net sales of ceramic electrostatic chucks for semiconductor manufacturing equipment grew due to increased demand against the backdrop of expanded capital investment in semiconductors for AI, etc. and other factors.
- Net sales of heat spreaders for CPUs grew due to increase in orders for servers.
- Net sales of glass-to-metal-seals were at almost the same level as the previous fiscal year for optical devices.
- Net sales of leadframes were at almost the same level as the previous fiscal year due to the progress of yen depreciation in the exchange rate and other factors, despite the impact of inventory adjustments for automobiles, etc.



Financial Results Overview of FY2024 (consolidated)

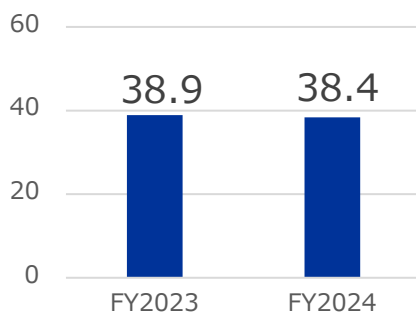
Net Sales by Product Category

(Billions of yen)

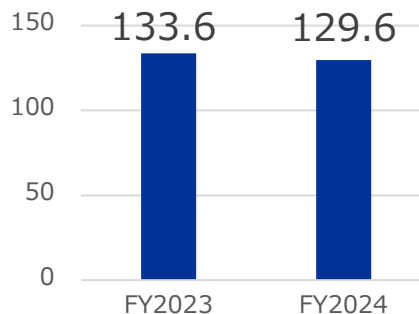
	FY2023 (Result)	FY2024 (Result)	YoY	
			Amount	Ratio of Change
IC Leadframes	38.9 [18%]*	38.4 [18%]*	-0.5	-1%
IC Packages	133.6 [64%]*	129.6 [60%]*	-3.9	-3%
Hermetic Seal Parts	37.5 [18%]*	47.0 [22%]*	+9.5	+25%

* Represent % of Net Sales

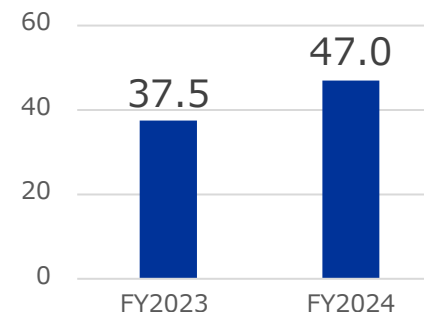
**Net Sales of
IC Leadframes**



**Net Sales of
IC Packages**



**Net Sales of
Hermetic Seal Parts**



Notice Concerning Result of the Tender Offer for the Company Shares by JICC-04, Ltd. and Upcoming Schedule

1. Result of the Tender Offer

As announced in “Notice Concerning Result of the Tender Offer for the Company Shares by JICC-04, Ltd. and Changes to Major Shareholder and Other Affiliated Companies” dated March 19, 2025, the Tender Offer for the Company’s common shares by JICC-04, Ltd. commenced on February 18, 2025 and completed on March 18, 2025. The total number of shares tendered was equal to or exceeded the minimum number of shares to be purchased (22,491,200 shares); accordingly, the Tender Offer was successfully completed.

2. Upcoming Schedule

JICC-04, Ltd. (the “Tender Offeror”) intends to carry out the series of procedures in order for the Tender Offeror to make the Company a wholly-owned subsidiary of the Tender Offeror. The Company’s shares will be delisted through the prescribed procedures in accordance with the stock delisting criteria of the Tokyo Stock Exchange.

● Date of Procedures (Schedule)

Extraordinary general meeting of shareholders (Share consolidation and partial amendment to articles of incorporation subject to the approval)	May 20, 2025 (Tuesday)
Date of designation of securities under supervision	May 20, 2025 (Tuesday)
Last day shares can be traded	June 5, 2025 (Thursday)
Delisting date	June 6, 2025 (Friday)
Effective date of the share consolidation	June 10, 2025 (Tuesday)

*** The Company’s shares are scheduled to be delisted on June 6, 2025, so the company has not announced forecasts of FY2025.**

Many numerical values are shown in units of a billion yen as a general outline of business performance in this material. Because original values, which are managed in units of a million yen, are round off, the totals, difference, etc. shown in these materials may appear inaccurate. For assumptions and the other information regarding the projections, please refer to “the Financial Results” on IR library of our corporate website.